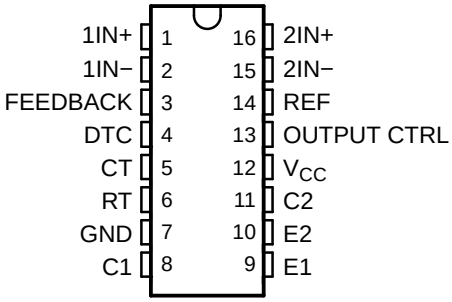
TL494
PULSE-WIDTH-MODULATION CONTROL CIRCUITS

SLVS074E – JANUARY 1983 – REVISED FEBRUARY 2005

FEATURES

- **Complete PWM Power-Control Circuitry**
- **Uncommitted Outputs for 200-mA Sink or Source Current**
- **Output Control Selects Single-Ended or Push-Pull Operation**
- **Internal Circuitry Prohibits Double Pulse at Either Output**
- **Variable Dead Time Provides Control Over Total Range**
- **Internal Regulator Provides a Stable 5-V Reference Supply With 5% Tolerance**
- **Circuit Architecture Allows Easy Synchronization**

D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



DESCRIPTION

The TL494 incorporates all the functions required in the construction of a pulse-width-modulation (PWM) control circuit on a single chip. Designed primarily for power-supply control, this device offers the flexibility to tailor the power-supply control circuitry to a specific application.

The TL494 contains two error amplifiers, an on-chip adjustable oscillator, a dead-time control (DTC) comparator, a pulse-steering control flip-flop, a 5-V, 5%-precision regulator, and output-control circuits.

The error amplifiers exhibit a common-mode voltage range from –0.3 V to V_{CC} – 2 V. The dead-time control comparator has a fixed offset that provides approximately 5% dead time. The on-chip oscillator can be bypassed by terminating RT to the reference output and providing a sawtooth input to CT, or it can drive the common circuits in synchronous multiple-rail power supplies.

The uncommitted output transistors provide either common-emitter or emitter-follower output capability. The TL494 provides for push-pull or single-ended output operation, which can be selected through the output-control function. The architecture of this device prohibits the possibility of either output being pulsed twice during push-pull operation.

The TL494C is characterized for operation from 0°C to 70°C. The TL494I is characterized for operation from –40°C to 85°C.

AVAILABLE OPTIONS

T_A	PACKAGED DEVICES(1)				
	SMALL OUTLINE (D)	PLASTIC DIP (N)	SMALL OUTLINE (NS)	SHRINK SMALL OUTLINE (DB)	THIN SHRINK SMALL OUTLINE (PW)
0°C to 70°C	TL494CD	TL494CN	TL494CNS	TL494CDB	TL494CPW
–40°C to 85°C	TL494ID	TL494IN	—	—	—

(1) The D, DB, NS, and PW packages are available taped and reeled. Add the suffix R to device type (e.g., TL494CDR).

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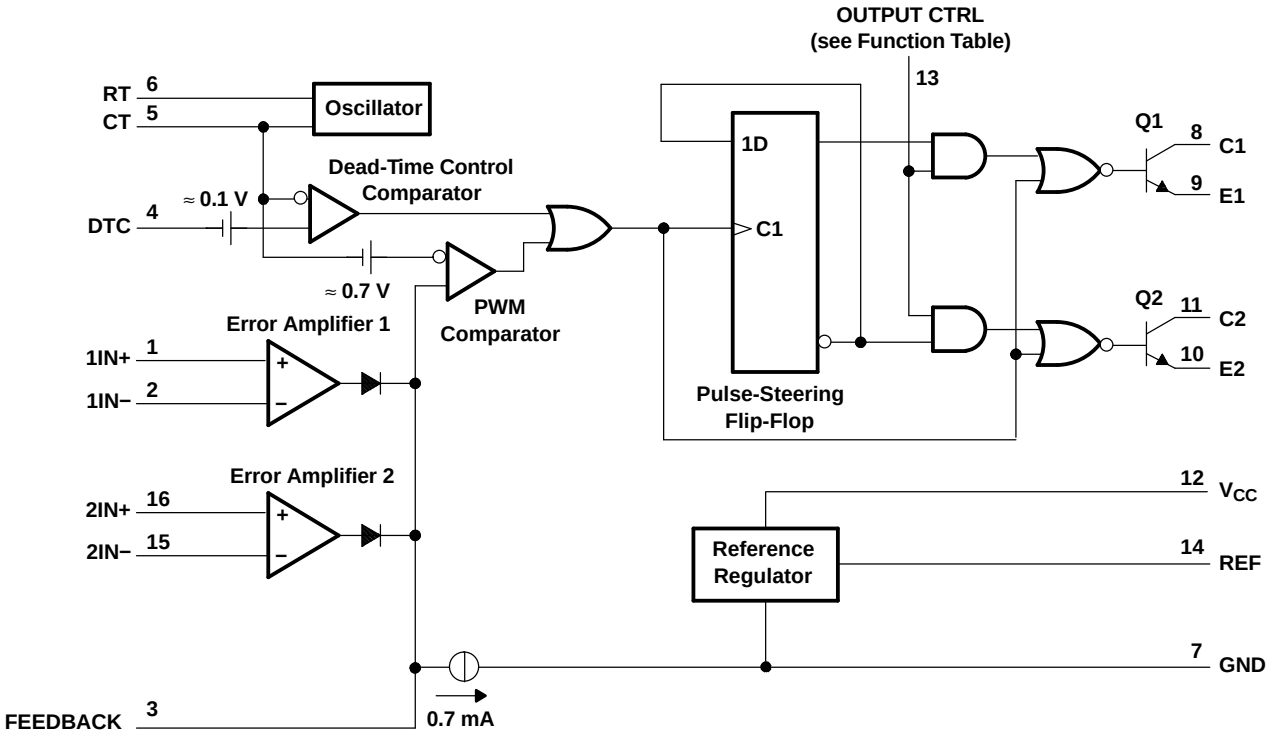
FUNCTION TABLE

INPUT TO OUTPUT CTRL	OUTPUT FUNCTION
V_I = GND	Single-ended or parallel output
$V_I = V_{ref}$	Normal push-pull operation

FUNCTIONAL BLOCK DIAGRAM



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage(2)			41	V
V_I	Amplifier input voltage			V_{CC} + 0.3	V
V_O	Collector output voltage			41	V
I_O	Collector output current			250	mA
θ_{JA}	Package thermal impedance(3)(4)	D package		73	°C/W
		DB package		82	
		N package		67	
		NS package		64	
		PW package		108	
	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds			260	°C
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltages are with respect to the network ground terminal.
(3) Maximum power disipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperatire is $P_D = (T_J(max) – T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions

			MIN	MAX	UNIT
V_{CC}	Supply voltage		7	40	V
V_I	Amplifier input voltage		–0.3	V_{CC} – 2	V
V_O	Collector output voltage			40	V
	Collector output current (each transistor)			200	mA
	Current into feedback terminal			0.3	mA
f_{OSC}	Oscillator frequency		1	300	kHz
C_T	Timing capacitor		0.47	10000	nF
R_T	Timing resistor		1.8	500	kΩ
T_A	Operating free-air temperature	TL494C	0	70	°C
		TL494I	–40	85	

Electrical Characteristics

over recommended operating free-air temperature range, V_{CC} = 15 V, f = 10 kHz (unless otherwise noted)

Reference Section

PARAMETER	TEST CONDITIONS(1)	TL494C, TL494I			UNIT
		MIN	TYP(2)	MAX	
Output voltage (REF)	I_O = 1 mA	4.75	5	5.25	V
Input regulation	V_{CC} = 7 V to 40 V		2	25	mV
Output regulation	I_O = 1 mA to 10 mA		1	15	mV
Output voltage change with temperature	ΔT_A = MIN to MAX		2	10	mV/V
Short-circuit output current(3)	REF = 0 V		25		mA

(1) For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
(2) All typical values, except for parameter changes with temperature, are at T_A = 25°C.
(3) Duration of short circuit should not exceed one second.

Oscillator Section

C_T = 0.01 μF, R_T = 12 kΩ (see Figure 1)

PARAMETER	TEST CONDITIONS(1)	TL494C, TL494I			UNIT
		MIN	TYP(2)	MAX	
Frequency			10		kHz
Standard deviation of frequency(3)	All values of V_{CC}, C_T, R_T, and T_A constant		100		Hz/kHz
Frequency change with voltage	V_{CC} = 7 V to 40 V, T_A = 25°C		1		Hz/kHz
Frequency change with temperature(4)	ΔT_A = MIN to MAX			10	Hz/kHz

(1) For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
(2) All typical values, except for parameter changes with temperature, are at T_A = 25°C.
(3) Standard deviation is a measure of the statistical distribution about the mean as derived from the formula:

$$\sigma = \sqrt{\frac{\sum_{n=1}^{N} (x_n - \overline{X})^2}{N - 1}}$$

(4) Temperature coefficient of timing capacitor and timing resistor are not taken into account.

Error-Amplifier Section

See Figure 2

PARAMETER	TEST CONDITIONS	TL494C, TL494I			UNIT
		MIN	TYP(1)	MAX	
Input offset voltage	V_O (FEEDBACK) = 2.5 V		2	10	mV
Input offset current	V_O (FEEDBACK) = 2.5 V		25	250	nA
Input bias current	V_O (FEEDBACK) = 2.5 V		0.2	1	μA
Common-mode input voltage range	V_{CC} = 7 V to 40 V	–0.3 to V_{CC} – 2			V
Open-loop voltage amplification	ΔV_O = 3 V, V_O = 0.5 V to 3.5 V, R_L = 2 kΩ	70	95		dB
Unity-gain bandwidth	V_O = 0.5 V to 3.5 V, R_L = 2 kΩ		800		kHz
Common-mode rejection ratio	ΔV_O = 40 V, T_A = 25°C	65	80		dB
Output sink current (FEEDBACK)	V_{ID} = –15 mV to –5 V, V (FEEDBACK) = 0.7 V	0.3	0.7		mA
Output source current (FEEDBACK)	V_{ID} = 15 mV to 5 V, V (FEEDBACK) = 3.5 V	–2			mA

(1) All typical values, except for parameter changes with temperature, are at T_A = 25°C.

Electrical Characteristics

over recommended operating free-air temperature range, V_{CC} = 15 V, f = 10 kHz (unless otherwise noted)

Output Section

PARAMETER		TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
Collector off-state current		V_{CE} = 40 V, V_{CC} = 40 V		2	100	μA
Emitter off-state current		V_{CC} = V_C = 40 V, V_E = 0			–100	μA
Collector-emitter saturation voltage	Common emitter	V_E = 0, I_C = 200 mA		1.1	1.3	V
	Emitter follower	$V_{O(C1 \text{ or } C2)}$ = 15 V, I_E = –200 mA		1.5	2.5	
Output control input current		V_I = V_{ref}			3.5	mA

(1) All typical values, except for temperature coefficient, are at T_A = 25°C.

Dead-Time Control Section

See Figure 1

PARAMETER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
Input bias current (DEAD-TIME CTRL)	V_I = 0 to 5.25 V		–2	–10	μA
Maximum duty cycle, each output	V_I (DEAD-TIME CTRL) = 0, C_T = 0.01 μF, R_T = 12 kΩ		45		%
Input threshold voltage (DEAD-TIME CTRL)	Zero duty cycle		3	3.3	V
	Maximum duty cycle	0			

(1) All typical values, except for temperature coefficient, are at T_A = 25°C.

PWM Comparator Section

See Figure 1

PARAMETER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
Input threshold voltage (FEEDBACK)	Zero duty cyle		4	4.5	V
Input sink current (FEEDBACK)	V (FEEDBACK) = 0.7 V	0.3	0.7		mA

(1) All typical values, except for temperature coefficient, are at T_A = 25°C.

Total Device

PARAMETER	TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
Standby supply current	R_T = V_{ref}, All other inputs and outputs open	V_{CC} = 15 V		6	10	mA
		V_{CC} = 40 V		9	15	
Average supply current	V_I (DEAD-TIME CTRL) = 2 V, See Figure 1			7.5		mA

(1) All typical values, except for temperature coefficient, are at T_A = 25°C.

Switching Characteristics

T_A = 25°C

PARAMETER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
Rise time	Common-emitter configuration, See Figure 3		100	200	ns
Fall time			25	100	ns
Rise time	Emitter-follower configuration, See Figure 4		100	200	ns
Fall time			40	100	ns

(1) All typical values, except for temperature coefficient, are at T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

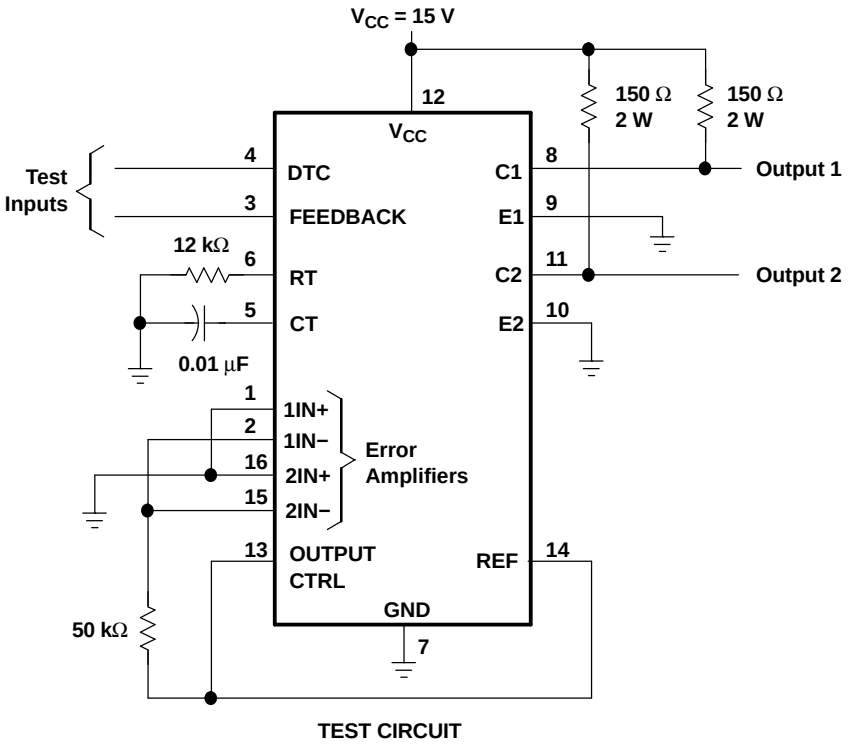


Figure 1. Operational Test Circuit and Waveforms

PARAMETER MEASUREMENT INFORMATION

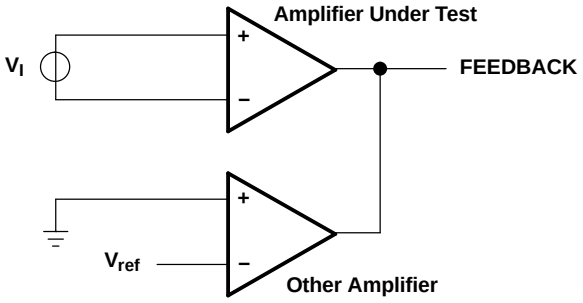
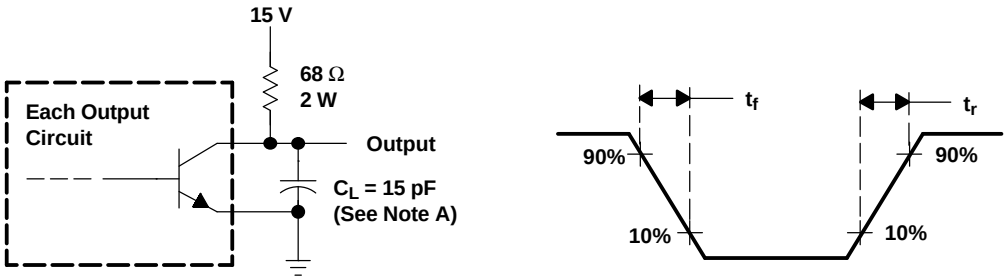
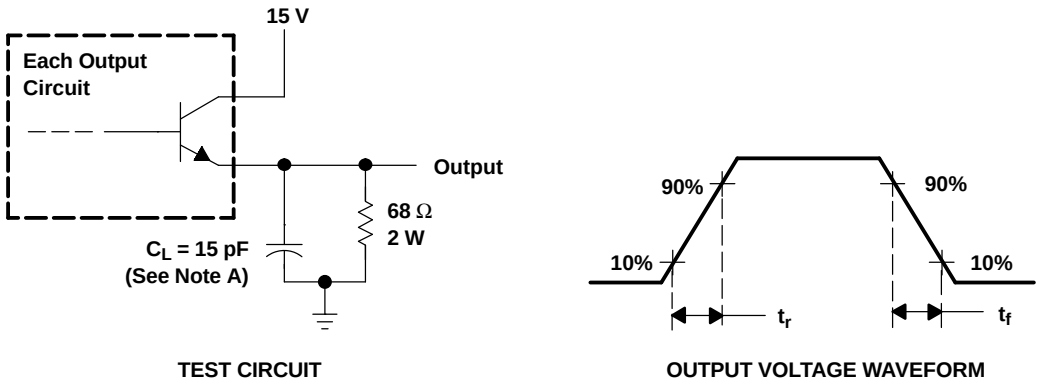


Figure 2. Amplifier Characteristics



NOTE A: C_L includes probe and jig capacitance.

Figure 3. Common-Emitter Configuration

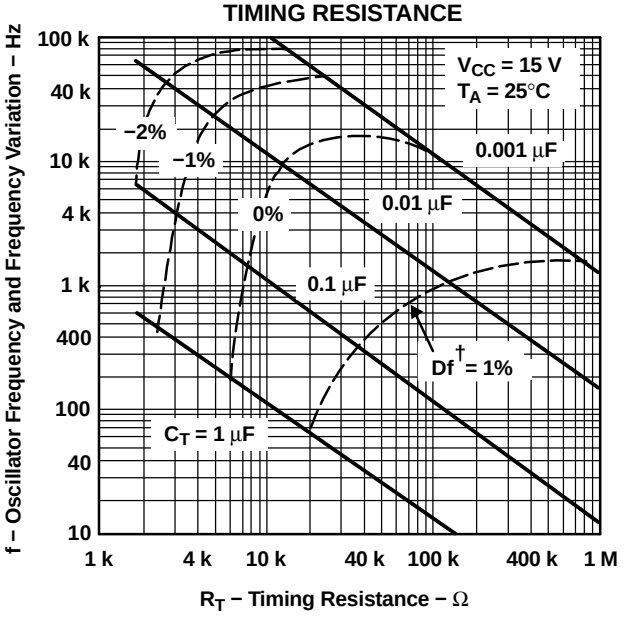


NOTE A: C_L includes probe and jig capacitance.

Figure 4. Emitter-Follower Configuration

TYPICAL CHARACTERISTICS

OSCILLATOR FREQUENCY AND FREQUENCY VARIATION† vs TIMING RESISTANCE



† Frequency variation (Δf) is the change in oscillator frequency that occurs over the full temperature range.

Figure 5.

AMPLIFIER VOLTAGE AMPLIFICATION vs FREQUENCY

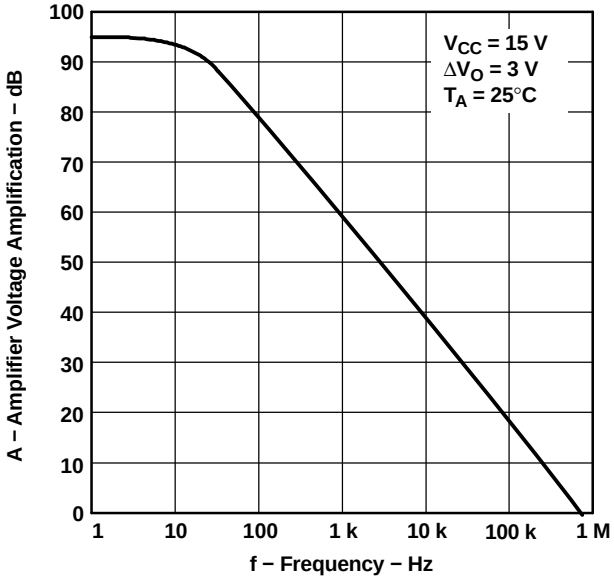


Figure 6.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TL494CD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CDRG3	PREVIEW	SOIC	D	16		TBD	Call TI	Call TI	
TL494CDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CJ	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
TL494CN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL494CNE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL494CNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CPWLE	OBSOLETE	TSSOP	PW	16		TBD	Call TI	Call TI	
TL494CPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494CPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/ Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
TL494ID	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494IDE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494IDG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494IDR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494IDRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494IDRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL494IN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL494INE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
TL494MJ	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	
TL494MJB	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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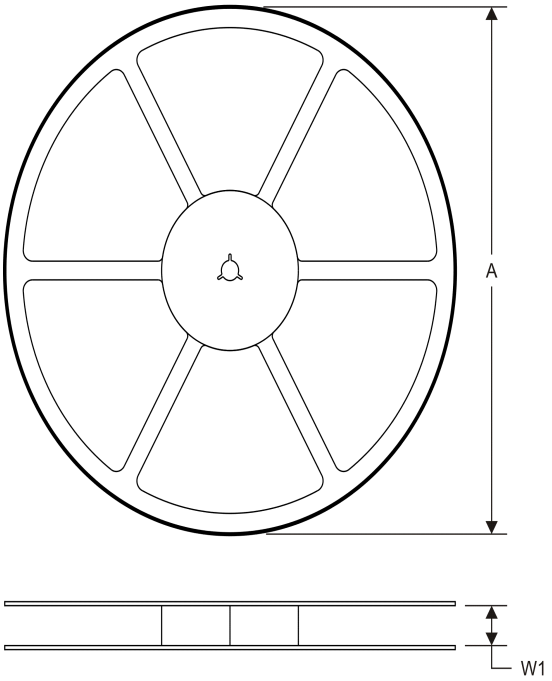
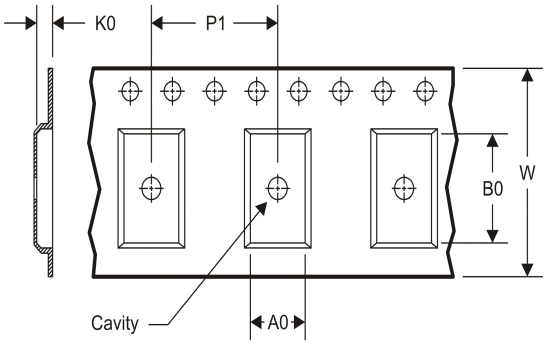
TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



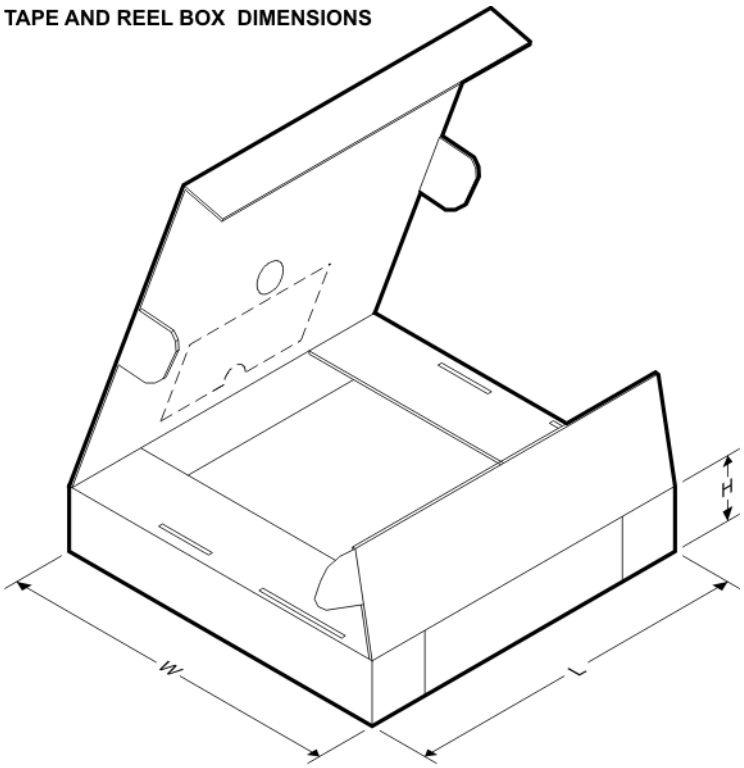
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL494CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TL494CDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TL494CDRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TL494CDRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
TL494CNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
TL494CPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
TL494IDR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



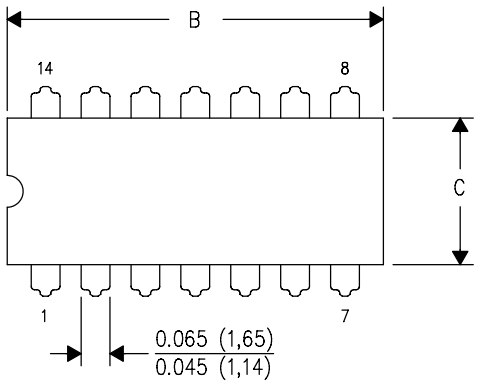
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL494CDR	SOIC	D	16	2500	333.2	345.9	28.6
TL494CDR	SOIC	D	16	2500	367.0	367.0	38.0
TL494CDRG4	SOIC	D	16	2500	333.2	345.9	28.6
TL494CDRG4	SOIC	D	16	2500	367.0	367.0	38.0
TL494CNSR	SO	NS	16	2000	367.0	367.0	38.0
TL494CPWR	TSSOP	PW	16	2000	367.0	367.0	35.0
TL494IDR	SOIC	D	16	2500	333.2	345.9	28.6

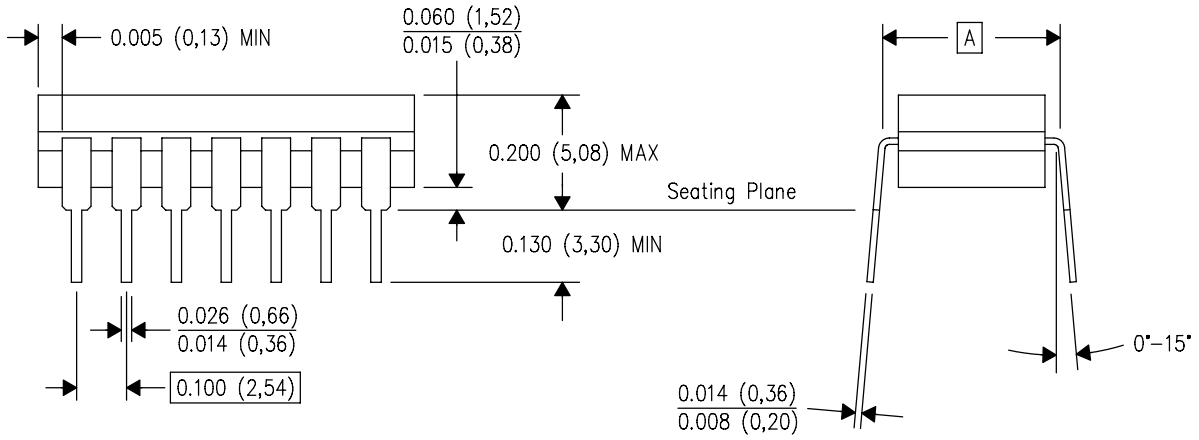
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



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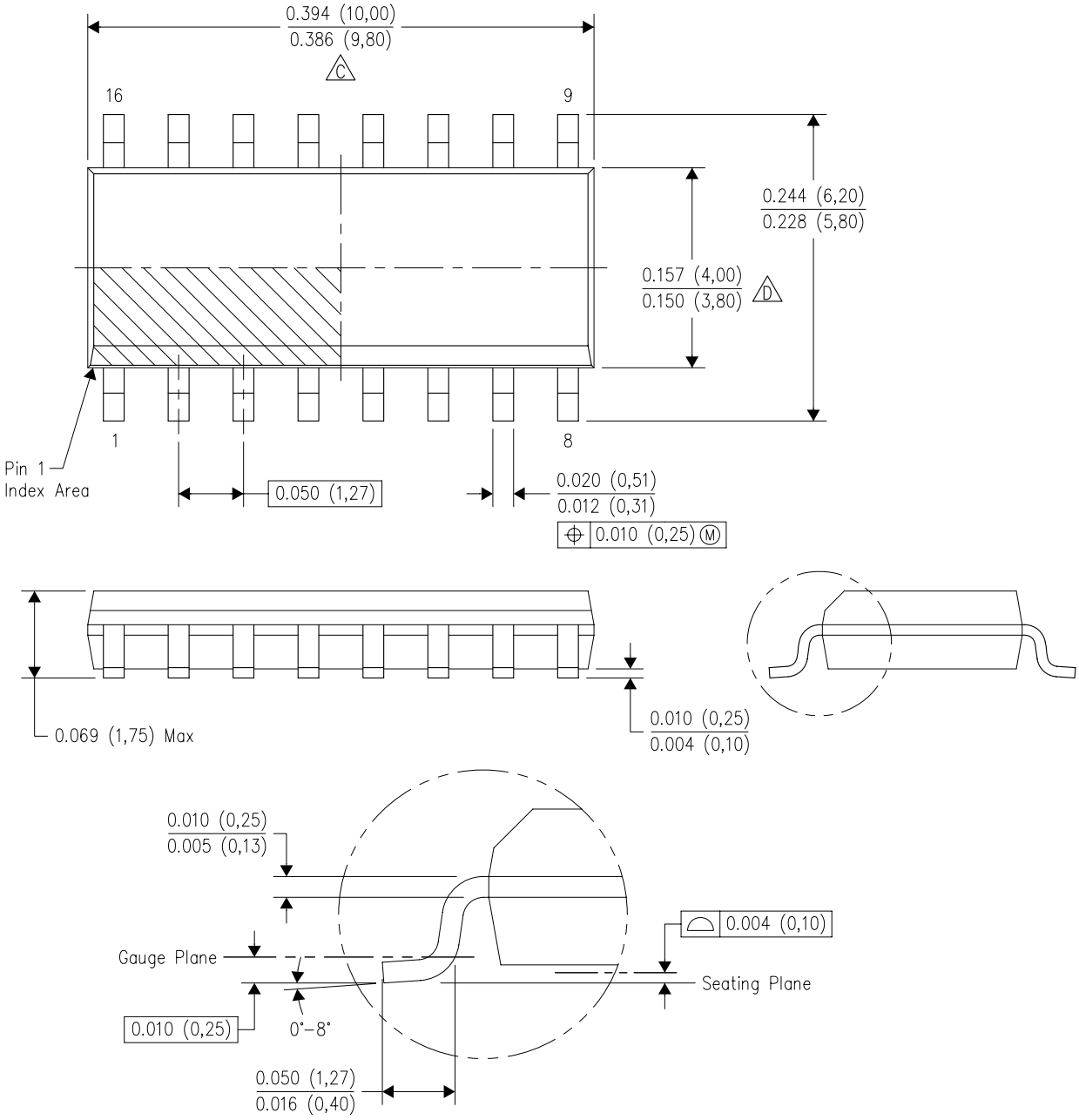
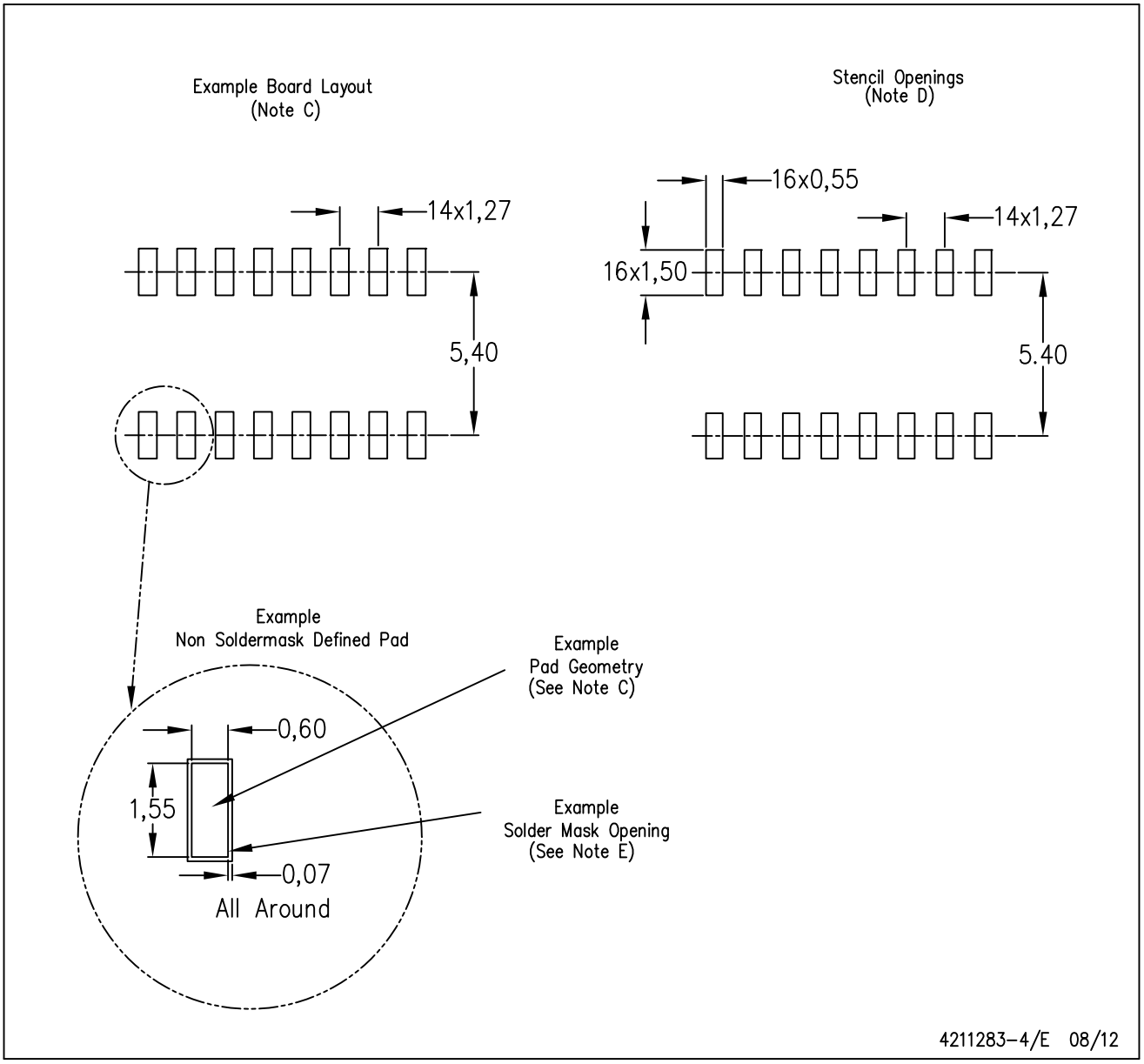
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



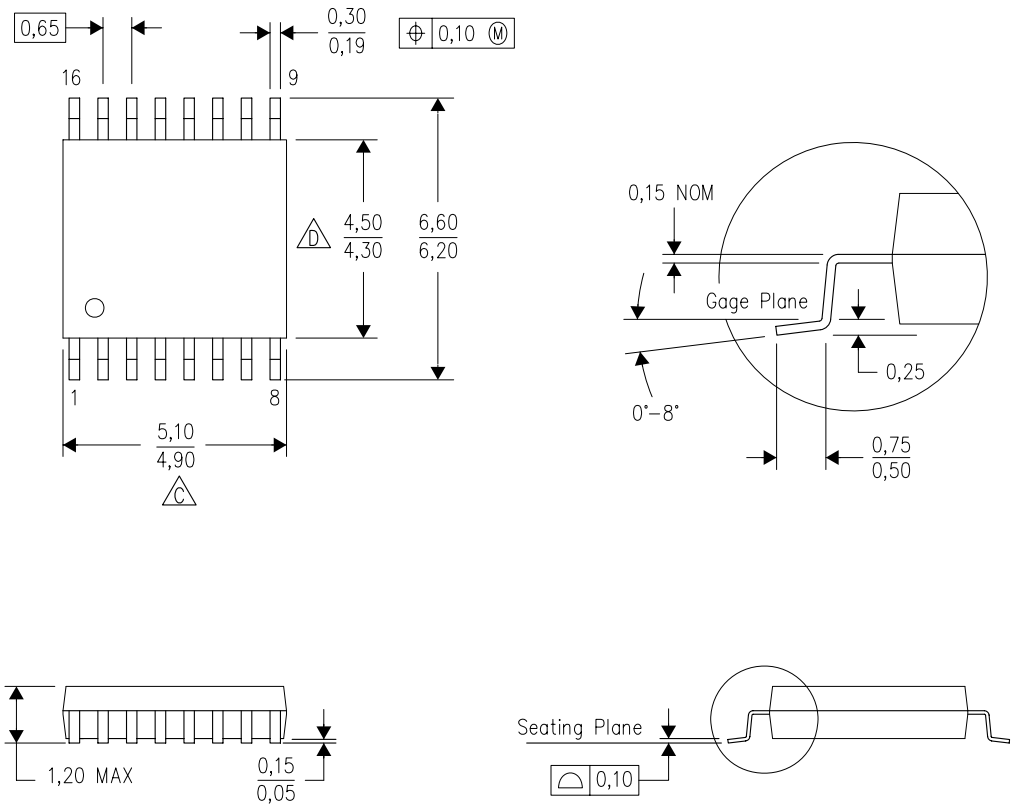
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

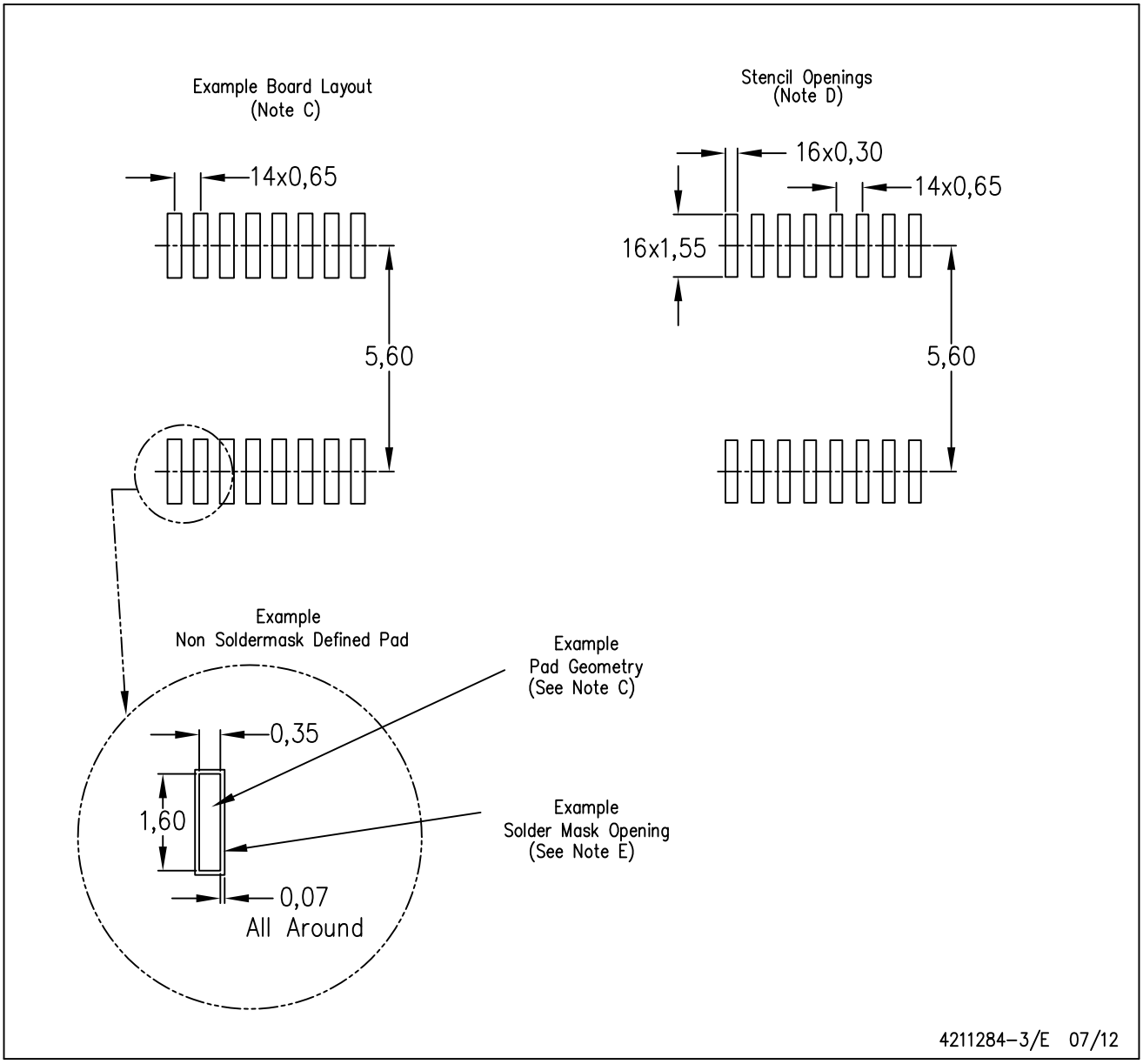
PW (R–PDSO–G16) PLASTIC SMALL OUTLINE



4040064–4/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G16) PLASTIC SMALL OUTLINE

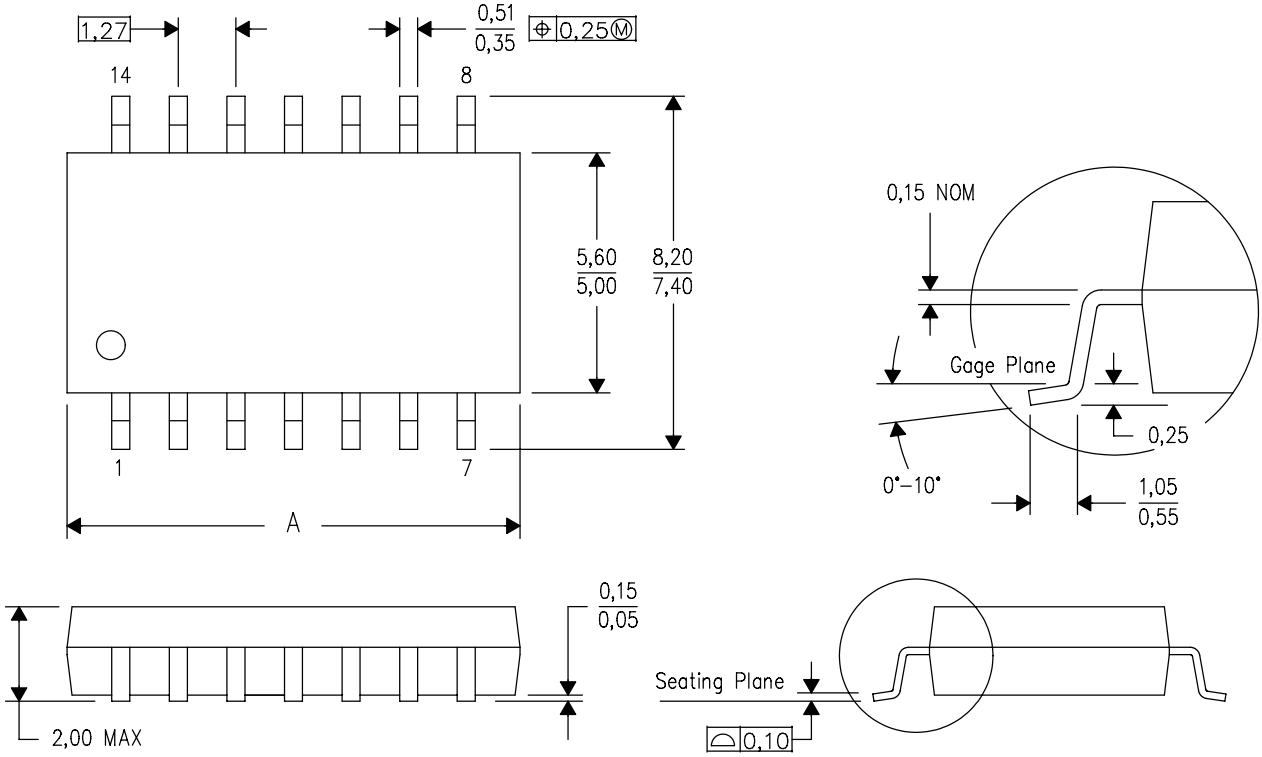


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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